

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YUE-DER CHIH</td> <td>05/27/2013</td> </tr> <tr> <td>HUNG-CHANG YU</td> <td>05/27/2013</td> </tr> <tr> <td>KAI-CHUN LIN</td> <td>08/27/2013</td> </tr> <tr> <td>CHIN-YI HUANG</td> <td>05/29/2013</td> </tr> <tr> <td>LAUN C. TRAN</td> <td>12/20/2013</td> </tr> </tbody> </table>		Name	Execution Date	YUE-DER CHIH	05/27/2013	HUNG-CHANG YU	05/27/2013	KAI-CHUN LIN	08/27/2013	CHIN-YI HUANG	05/29/2013	LAUN C. TRAN	12/20/2013
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CHIN-YI HUANG	05/29/2013												
LAUN C. TRAN	12/20/2013												
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City:	HSIN-CHU												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13917772</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13917772								
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CORRESPONDENCE DATA													
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ATTORNEY DOCKET NUMBER:	TSMCP218USA												

NAME OF SUBMITTER:	THOMAS G. ESCHWEILER
Signature:	/Thomas G. Eschweiler/
Date:	01/07/2014
<b>Total Attachments: 7</b> source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif source=Assignment#page6.tif source=Assignment#page7.tif	

TSMC Docket No. TSMC2012-1095

U.S. Patent Appln. No.

Docket No. TSMCP218USA

Filing Date

PATENT ASSIGNMENT

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**AGREEMENT**

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled  
**“MRAM SMART BIT WRITE ALGORITHM WITH ERROR CORRECTION  
PARITY BITS”** for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

was filed on \_\_\_\_\_ and accorded U.S. Serial No. \_\_\_\_\_; or

I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. \_\_\_\_\_,

filed on \_\_\_\_\_.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of

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ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

5/29/2013

Date

*Yue Der Chih*

Name 1<sup>st</sup> Inventor Yue-Der Chih

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U.S. Patent Appl. No.

Filing Date

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Date

Hung-Chang Yu

Name 2<sup>nd</sup> Inventor Hung-Chang Yu

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8/27/2013  
Date

Kai-Chun Lin  
Name 3<sup>rd</sup> Inventor Kai-Chun Lin

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Filing Date



May 29th 2013

Date

Chin Yi Huang

Name 4<sup>th</sup> Inventor Chin-Yi Huang



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TSMC Docket No. TSMC2012-1095

Docket No. TSMCP218USA

Dec 20<sup>th</sup>, 2013  
Date

Luan C. Tran  
Name 5<sup>th</sup> Inventor Luan C. Tran